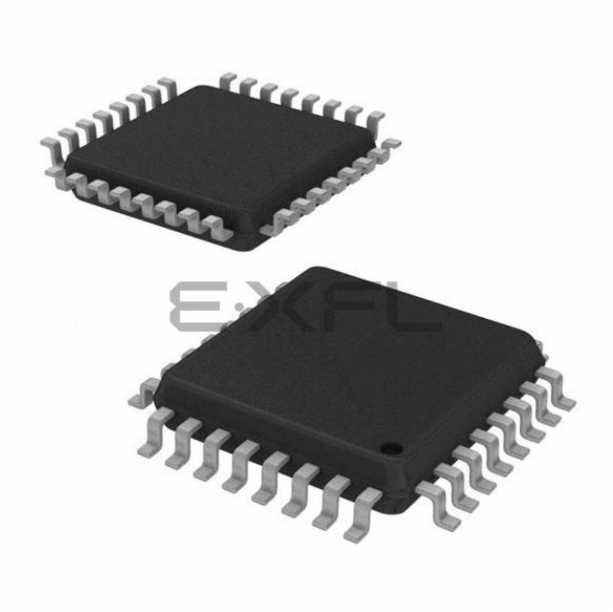


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I²C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08dv16vlc

Chapter 7
Central Processor Unit (S08CPUV3)

Chapter 8
Multi-Purpose Clock Generator (S08MCGV1)

Chapter 4
Memory

4.1 MC9S08DV60 Series Memory Map

On-chip memory in the MC9S08DV60 Series consists of RAM and Flash program memory for nonvolatile data storage, and I/O and control/status registers. The registers are divided into three groups:

- Direct-page registers (0x0000 through 0x007F)
- High-page registers (0x1800 through 0x18FF)
- Nonvolatile registers (0xFFB0 through 0xFFBF)

4.3 Register Addresses and Bit Assignments

The registers in the MC9S08DV60 Series are divided into these groups:

- Direct-page registers are located in the first 128 locations in the memory map; these are accessible with efficient direct addressing mode instructions.
- High-page registers are used much less often, so they are located above 0x1800 in the memory map. This leaves more room in the direct page for more frequently used registers and RAM.
- The nonvolatile register area consists of a block of 16 locations in Flash memory at 0xFFB0–0xFFBF. Nonvolatile register locations include:
  - NVPROT and NVOPT are loaded into working registers at reset
  - An 8-byte backdoor comparison key that optionally allows a user to gain controlled access to secure memory

  Because the nonvolatile register locations are Flash memory, they must be erased and programmed like other Flash memory locations.

Direct-page registers can be accessed with efficient direct addressing mode instructions. Bit manipulation instructions can be used to access any bit in any direct-page register. Table 4-2 is a summary of all user-accessible direct-page registers and control bits.

The direct page registers in Table 4-2 can use the more efficient direct addressing mode, which requires only the lower byte of the address. Because of this, the lower byte of the address in column one is shown in bold text. In Table 4-3 and Table 4-5, the whole address in column one is shown in bold. In Table 4-2, Table 4-3, and Table 4-5, the register names in column two are shown in bold to set them apart from the bit names to the right. Cells that are not associated with named bits are shaded. A shaded cell with a 0 indicates this unused bit always reads as a 0. Shaded cells with dashes indicate unused or reserved bit locations that could read as 1s or 0s.

Table 4-2. Direct-Page Register Summary (Sheet 1 of 3)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x0000	PTAD	PTAD7	PTAD6	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
0x0001	PTADD	PTADD7	PTADD6	PTADD5	PTADD4	PTADD3	PTADD2	PTADD1	PTADD0
0x0002	PTBD	PTBD7	PTBD6	PTBD5	PTBD4	PTBD3	PTBD2	PTBD1	PTBD0
0x0003	PTBDD	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0
0x0004	PTCD	PTCD7	PTCD6	PTCD5	PTCD4	PTCD3	PTCD2	PTCD1	PTCD0
0x0005	PTCDD	PTCDD7	PTCDD6	PTCDD5	PTCDD4	PTCDD3	PTCDD2	PTCDD1	PTCDD0
0x0006	PTDD	PTDD7	PTDD6	PTDD5	PTDD4	PTDD3	PTDD2	PTDD1	PTDD0
0x0007	PTDDD	PTDDD7	PTDDD6	PTDDD5	PTDDD4	PTDDD3	PTDDD2	PTDDD1	PTDDD0
0x0008	PTED	PTED7	PTED6	PTED5	PTED4	PTED3	PTED2	PTED1	PTED0
0x0009	PTEDD	PTEDD7	PTEDD6	PTEDD5	PTEDD4	PTEDD3	PTEDD2	PTEDD1	PTEDD0
0x000A	PTFD	PTFD7	PTFD6	PTFD5	PTFD4	PTFD3	PTFD2	PTFD1	PTFD0
0x000B	PTFDD	PTFDD7	PTFDD6	PTFDD5	PTFDD4	PTFDD3	PTFDD2	PTFDD1	PTFDD0
0x000C	PTGD	0	0	PTGD5	PTGD4	PTGD3	PTGD2	PTGD1	PTGD0
0x000D	PTGDD	0	0	PTGDD5	PTGDD4	PTGDD3	PTGDD2	PTGDD1	PTGDD0
0x000E	ACMP1SC	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACMOD1	ACMOD0
0x000F	ACMP2SC	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACMOD1	ACMOD0
0x0010	ADCSC1	COCO	AIEN	ADCO	ADCH				
0x0011	ADCSC2	ADACT	ADTRG	ACFE	ACFGT	0	0	—	—
0x0012	ADCRH	0	0	0	0	ADR11	ADR10	ADR9	ADR8
0x0013	ADCRL	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0
0x0014	ADCCVH	0	0	0	0	ADCV11	ADCV10	ADCV9	ADCV8
0x0015	ADCCVL	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0
0x0016	ADCCFG	ADLPC	ADIV		ADLSMP	MODE		ADICLK	
0x0017	APCTL1	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
0x0018	APCTL2	ADPC15	ADPC14	ADPC13	ADPC12	ADPC11	ADPC10	ADPC9	ADPC8
0x0019	APCTL3	ADPC23	ADPC22	ADPC21	ADPC20	ADPC19	ADPC18	ADPC17	ADPC16
0x001A– 0x001B	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x001C	IRQSC	0	IRQPDD	IRQEDG	IRQPE	IRQF	IRQACK	IRQIE	IRQMOD
0x001D– 0x001F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0020	TPM1SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0021	TPM1CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x0022	TPM1CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x0023	TPM1MODH	Bit 15	14	13	12	11	10	9	Bit 8
0x0024	TPM1MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x0025	TPM1C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0026	TPM1C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0027	TPM1C0VL	Bit 7	6	5	4	3	2	1	Bit 0

Table 4-2. Direct-Page Register Summary (Sheet 2 of 3)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x0028	**TPM1C1SC**	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x0029	**TPM1C1VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x002A	**TPM1C1VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x002B	**TPM1C2SC**	CH2F	CH2IE	MS2B	MS2A	ELS2B	ELS2A	0	0
0x002C	**TPM1C2VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x002D	**TPM1C2VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x002E	**TPM1C3SC**	CH3F	CH3IE	MS3B	MS3A	ELS3B	ELS3A	0	0
0x002F	**TPM1C3VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x0030	**TPM1C3VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x0031	**TPM1C4SC**	CH4F	CH4IE	MS4B	MS4A	ELS4B	ELS4A	0	0
0x0032	**TPM1C4VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x0033	**TPM1C4VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x0034	**TPM1C5SC**	CH5F	CH5IE	MS5B	MS5A	ELS5B	ELS5A	0	0
0x0035	**TPM1C5VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x0036	**TPM1C5VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x0037	Reserved	—	—	—	—	—	—	—	—
0x0038	**SCI1BDH**	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x0039	**SCI1BDL**	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x003A	**SCI1C1**	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
0x003B	**SCI1C2**	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x003C	**SCI1S1**	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x003D	**SCI1S2**	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
0x003E	**SCI1C3**	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x003F	**SCI1D**	Bit 7	6	5	4	3	2	1	Bit 0
0x0040	**SCI2BDH**	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x0041	**SCI2BDL**	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x0042	**SCI2C1**	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
0x0043	**SCI2C2**	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x0044	**SCI2S1**	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x0045	**SCI2S2**	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
0x0046	**SCI2C3**	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x0047	**SCI2D**	Bit 7	6	5	4	3	2	1	Bit 0
0x0048	**MCGC1**	CLKS		RDIV			IREFS	IRCLKEN	IREFSTEN
0x0049	**MCGC2**	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
0x004A	**MCGTRM**	TRIM							
0x004B	**MCGSC**	LOLS	LOCK	PLLST	IREFST	CLKST		OSCINIT	FTRIM
0x004C	**MCGC3**	LOLIE	PLLS	CME	0	VDIV			
0x004D– 0x004F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —

4.4 RAM

The MC9S08DV60 Series includes static RAM. The locations in RAM below 0x0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data while the MCU is in low-power wait, stop2, or stop3 mode. At power-on the contents of RAM are uninitialized. RAM data is unaffected by any reset if the supply voltage does not drop below the minimum value for RAM retention (V_{RAM}).

For compatibility with M68HC05 MCUs, the HCS08 resets the stack pointer to 0x00FF. In the MC9S08DV60 Series, it is usually best to reinitialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following 2-instruction sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM in the Freescale Semiconductor equate file).

```
LDHX     #RamLast+1    ;point one past RAM
TXS                    ;SP<-(H:X-1)
```

When security is enabled, the RAM is considered a secure memory resource and is not accessible through BDM or code executing from non-secure memory. See Section 4.5.9, “Security”, for a detailed description of the security feature.

4.5 Flash

MC9S08DV60 Series devices include Flash memory intended primarily for program and data storage. In-circuit programming allows the operating program and data to be loaded into Flash after final assembly of the application product. It is possible to program the arrays through the single-wire background debug interface. Because no special voltages are needed for erase and programming operations, in-application programming is also possible through other software-controlled communication paths. For a more detailed discussion of in-circuit and in-application programming, refer to the *HCS08 Family Reference Manual, Volume I,* Freescale Semiconductor document order number HCS08RMv1.

4.5.1 Features

Features of the Flash include:

- Array size (see Table 1-1 for exact array sizes)
- Flash sector size: 768 bytes
- Single power supply program and erase
- Command interface for fast program and erase operation
- Up to 100,000 program/erase cycles at typical voltage and temperature
- Flexible block protection and vector redirection
- Security feature for Flash and RAM
- Burst programming capability
- Sector erase abort

- LP bit is written to 0

In FLL bypassed internal mode, the MCGOUT clock is derived from the internal reference clock. The FLL clock is controlled by the internal reference clock, and the FLL clock frequency locks to 1024 times the reference frequency, as selected by the RDIV bits. The MCGLCLK is derived from the FLL and the PLL is disabled in a low power state.

8.4.1.4 FLL Bypassed External (FBE)

In FLL bypassed external (FBE) mode, the MCGOUT clock is derived from the external reference clock and the FLL is operational but its output clock is not used. This mode is useful to allow the FLL to acquire its target frequency while the MCGOUT clock is driven from the external reference clock.

The FLL bypassed external mode is entered when all the following conditions occur:

- CLKS bits are written to 10
- IREFS bit is written to 0
- PLLS bit is written to 0
- RDIV bits are written to divide reference clock to be within the range of 31.25 kHz to 39.0625 kHz
- LP bit is written to 0

In FLL bypassed external mode, the MCGOUT clock is derived from the external reference clock. The external reference clock which is enabled can be an external crystal/resonator or it can be another external clock source.The FLL clock is controlled by the external reference clock, and the FLL clock frequency locks to 1024 times the reference frequency, as selected by the RDIV bits. The MCGLCLK is derived from the FLL and the PLL is disabled in a low power state.

NOTE

It is possible to briefly operate in FBE mode with an FLL reference clock frequency that is greater than the specified maximum frequency. This can be necessary in applications that operate in PEE mode using an external crystal with a frequency above 5 MHz. Please see 8.5.2.4, “Example # 4: Moving from FEI to PEE Mode: External Crystal = 8 MHz, Bus Frequency = 8 MHz for a detailed example.

8.4.1.5 PLL Engaged External (PEE)

The PLL engaged external (PEE) mode is entered when all the following conditions occur:

- CLKS bits are written to 00
- IREFS bit is written to 0
- PLLS bit is written to 1
- RDIV bits are written to divide reference clock to be within the range of 1 MHz to 2 MHz

In PLL engaged external mode, the MCGOUT clock is derived from the PLL clock which is controlled by the external reference clock. The external reference clock which is enabled can be an external crystal/resonator or it can be another external clock source The PLL clock frequency locks to a

Table 10-12. APCTL3 Register Field Descriptions

Field	Description
7 ADPC23	ADC Pin Control 23. ADPC23 controls the pin associated with channel AD23. 0 AD23 pin I/O control enabled 1 AD23 pin I/O control disabled
6 ADPC22	ADC Pin Control 22. ADPC22 controls the pin associated with channel AD22. 0 AD22 pin I/O control enabled 1 AD22 pin I/O control disabled
5 ADPC21	ADC Pin Control 21. ADPC21 controls the pin associated with channel AD21. 0 AD21 pin I/O control enabled 1 AD21 pin I/O control disabled
4 ADPC20	ADC Pin Control 20. ADPC20 controls the pin associated with channel AD20. 0 AD20 pin I/O control enabled 1 AD20 pin I/O control disabled
3 ADPC19	ADC Pin Control 19. ADPC19 controls the pin associated with channel AD19. 0 AD19 pin I/O control enabled 1 AD19 pin I/O control disabled
2 ADPC18	ADC Pin Control 18. ADPC18 controls the pin associated with channel AD18. 0 AD18 pin I/O control enabled 1 AD18 pin I/O control disabled
1 ADPC17	ADC Pin Control 17. ADPC17 controls the pin associated with channel AD17. 0 AD17 pin I/O control enabled 1 AD17 pin I/O control disabled
0 ADPC16	ADC Pin Control 16. ADPC16 controls the pin associated with channel AD16. 0 AD16 pin I/O control enabled 1 AD16 pin I/O control disabled

10.4 Functional Description

The ADC module is disabled during reset or when the ADCH bits are all high. The module is idle when a conversion has completed and another conversion has not been initiated. When idle, the module is in its lowest power state.

The ADC can perform an analog-to-digital conversion on any of the software selectable channels. In 12-bit and 10-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 12-bit digital result. In 8-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 9-bit digital result.

When the conversion is completed, the result is placed in the data registers (ADCRH and ADCRL). In 10-bit mode, the result is rounded to 10 bits and placed in the data registers (ADCRH and ADCRL). In 8-bit mode, the result is rounded to 8 bits and placed in ADCRL. The conversion complete flag (COCO) is then set and an interrupt is generated if the conversion complete interrupt has been enabled (AIEN = 1).

The ADC module has the capability of automatically comparing the result of a conversion with the contents of its compare registers. The compare function is enabled by setting the ACFE bit and operates with any of the conversion modes and configurations.

11.3.5 IIC Data I/O Register (IICD)

	7	6	5	4	3	2	1	0
R	DATA							
W								
Reset	0	0	0	0	0	0	0	0

Figure 11-7. IIC Data I/O Register (IICD)

Table 11-7. IICD Field Descriptions

Field	Description
7–0 DATA	**Data** — In master transmit mode, when data is written to the IICD, a data transfer is initiated. The most significant bit is sent first. In master receive mode, reading this register initiates receiving of the next byte of data.

NOTE

> When transitioning out of master receive mode, the IIC mode should be switched before reading the IICD register to prevent an inadvertent initiation of a master receive data transfer.

In slave mode, the same functions are available after an address match has occurred.

The TX bit in IICC must correctly reflect the desired direction of transfer in master and slave modes for the transmission to begin. For instance, if the IIC is configured for master transmit but a master receive is desired, reading the IICD does not initiate the receive.

Reading the IICD returns the last byte received while the IIC is configured in master receive or slave receive modes. The IICD does not reflect every byte transmitted on the IIC bus, nor can software verify that a byte has been written to the IICD correctly by reading it back.

In master transmit mode, the first byte of data written to IICD following assertion of MST is used for the address transfer and should comprise of the calling address (in bit 7 to bit 1) concatenated with the required R/$\overline{\text{W}}$ bit (in position bit 0).

11.3.6 IIC Control Register 2 (IICC2)

	7	6	5	4	3	2	1	0
R	GCAEN	ADEXT	0	0	0	AD10	AD9	AD8
W			▨	▨	▨			
Reset	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 11-8. IIC Control Register (IICC2)

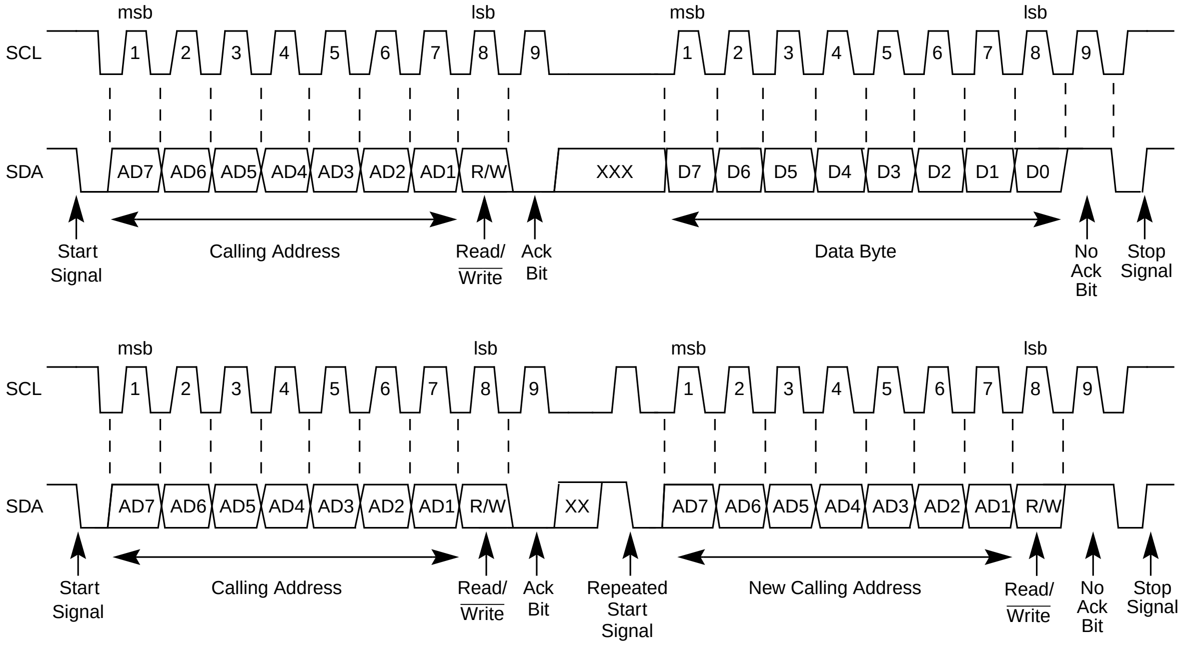


Figure 11-9. IIC Bus Transmission Signals

11.4.1.1 Start Signal

When the bus is free, no master device is engaging the bus (SCL and SDA lines are at logical high), a master may initiate communication by sending a start signal. As shown in Figure 11-9, a start signal is defined as a high-to-low transition of SDA while SCL is high. This signal denotes the beginning of a new data transfer (each data transfer may contain several bytes of data) and brings all slaves out of their idle states.

11.4.1.2 Slave Address Transmission

The first byte of data transferred immediately after the start signal is the slave address transmitted by the master. This is a seven-bit calling address followed by a R/$\overline{\text{W}}$ bit. The R/$\overline{\text{W}}$ bit tells the slave the desired direction of data transfer.

1 = Read transfer, the slave transmits data to the master.
0 = Write transfer, the master transmits data to the slave.

Only the slave with a calling address that matches the one transmitted by the master responds by sending back an acknowledge bit. This is done by pulling the SDA low at the ninth clock (see Figure 11-9).

No two slaves in the system may have the same address. If the IIC module is the master, it must not transmit an address equal to its own slave address. The IIC cannot be master and slave at the same time. However, if arbitration is lost during an address cycle, the IIC reverts to slave mode and operates correctly even if it is being addressed by another master.

11.4.3 General Call Address

General calls can be requested in 7-bit address or 10-bit address. If the GCAEN bit is set, the IIC matches the general call address as well as its own slave address. When the IIC responds to a general call, it acts as a slave-receiver and the IAAS bit is set after the address cycle. Software must read the IICD register after the first byte transfer to determine whether the address matches is its own slave address or a general call. If the value is 00, the match is a general call. If the GCAEN bit is clear, the IIC ignores any data supplied from a general call address by not issuing an acknowledgement.

11.5 Resets

The IIC is disabled after reset. The IIC cannot cause an MCU reset.

11.6 Interrupts

The IIC generates a single interrupt.

An interrupt from the IIC is generated when any of the events in Table 11-11 occur, provided the IICIE bit is set. The interrupt is driven by bit IICIF (of the IIC status register) and masked with bit IICIE (of the IIC control register). The IICIF bit must be cleared by software by writing a 1 to it in the interrupt routine. You can determine the interrupt type by reading the status register.

Table 11-11. Interrupt Summary

Interrupt Source	Status	Flag	Local Enable
Complete 1-byte transfer	TCF	IICIF	IICIE
Match of received calling address	IAAS	IICIF	IICIE
Arbitration Lost	ARBL	IICIF	IICIE

11.6.1 Byte Transfer Interrupt

The TCF (transfer complete flag) bit is set at the falling edge of the ninth clock to indicate the completion of byte transfer.

11.6.2 Address Detect Interrupt

When the calling address matches the programmed slave address (IIC address register) or when the GCAEN bit is set and a general call is received, the IAAS bit in the status register is set. The CPU is interrupted, provided the IICIE is set. The CPU must check the SRW bit and set its Tx mode accordingly.

11.6.3 Arbitration Lost Interrupt

The IIC is a true multi-master bus that allows more than one master to be connected on it. If two or more masters try to control the bus at the same time, the relative priority of the contending masters is determined by a data arbitration procedure. The IIC module asserts this interrupt when it loses the data arbitration process and the ARBL bit in the status register is set.

Table 12-5. Baud Rate Prescaler

BRP5	BRP4	BRP3	BRP2	BRP1	BRP0	Prescaler value (P)
0	0	0	0	0	0	1
0	0	0	0	0	1	2
0	0	0	0	1	0	3
0	0	0	0	1	1	4
:	:	:	:	:	:	:
1	1	1	1	1	1	64

12.3.4 MSCAN Bus Timing Register 1 (CANBTR1)

The CANBTR1 register configures various CAN bus timing parameters of the MSCAN module.

	7	6	5	4	3	2	1	0
R W	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
Reset:	0	0	0	0	0	0	0	0

Figure 12-7. MSCAN Bus Timing Register 1 (CANBTR1)

Read: Anytime
Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

Table 12-6. CANBTR1 Register Field Descriptions

Field	Description
7 SAMP	**Sampling** — This bit determines the number of CAN bus samples taken per bit time. 0 One sample per bit. 1 Three samples per bit[1]. If SAMP = 0, the resulting bit value is equal to the value of the single bit positioned at the sample point. If SAMP = 1, the resulting bit value is determined by using majority rule on the three total samples. For higher bit rates, it is recommended that only one sample is taken per bit time (SAMP = 0).
6:4 TSEG2[2:0]	**Time Segment 2** — Time segments within the bit time fix the number of clock cycles per bit time and the location of the sample point (see Figure 12-43). Time segment 2 (TSEG2) values are programmable as shown in Table 12-7.
3:0 TSEG1[3:0]	**Time Segment 1** — Time segments within the bit time fix the number of clock cycles per bit time and the location of the sample point (see Figure 12-43). Time segment 1 (TSEG1) values are programmable as shown in Table 12-8.

---

[1] In this case, PHASE_SEG1 must be at least 2 time quanta (Tq).

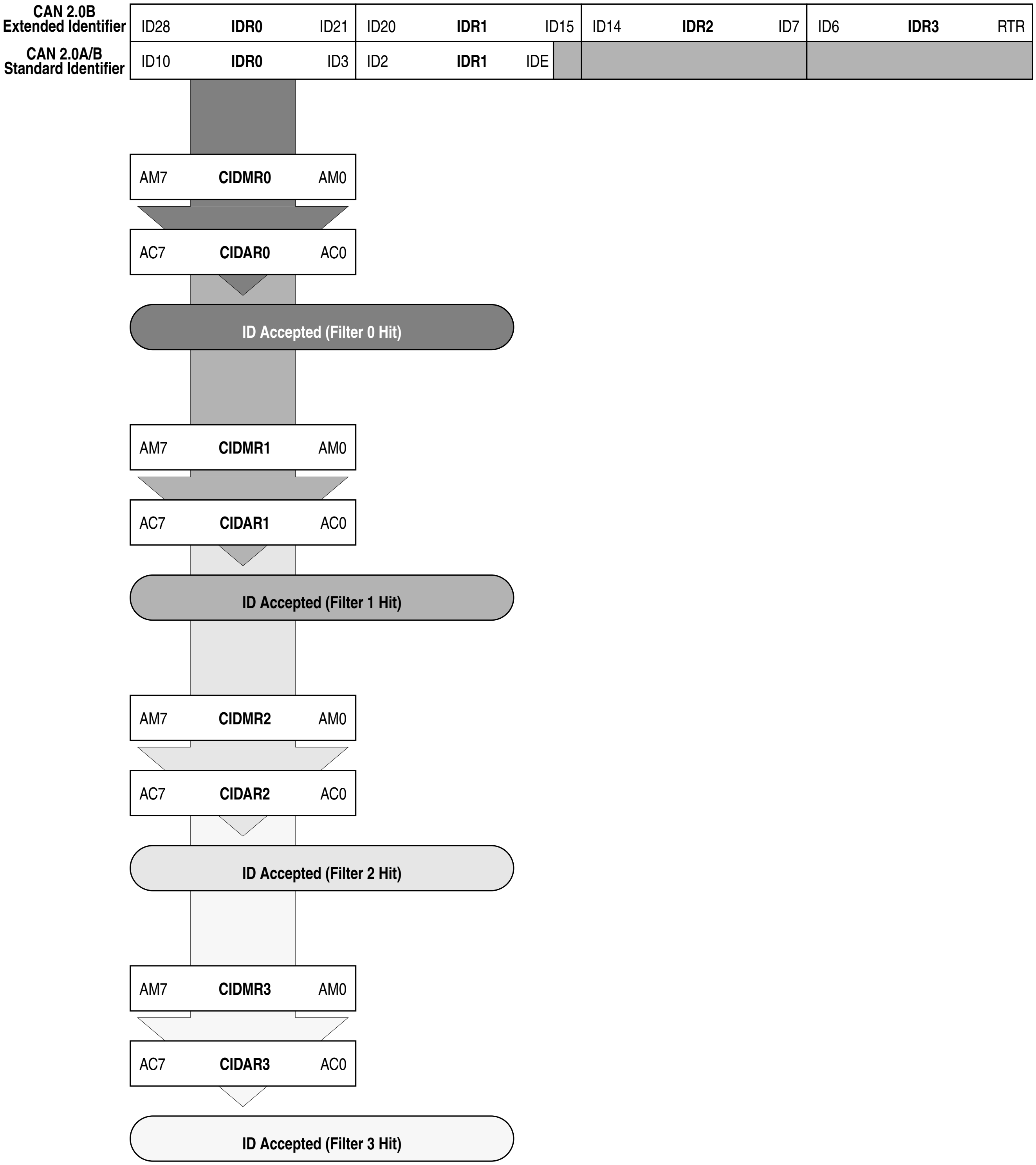


Figure 12-41. 8-bit Maskable Identifier Acceptance Filters

MSCAN filter uses three sets of registers to provide the filter configuration. Firstly, the CANIDAC register determines the configuration of the banks into filter sizes and number of filters. Secondly, registers CANIDMR0/1/2/3 determine those bits on which the filter will operate by placing a '0' at the appropriate

The MSCAN is able to leave sleep mode (wake up) only when:

- CAN bus activity occurs and WUPE = 1

  or
- the CPU clears the SLPRQ bit

NOTE

The CPU cannot clear the SLPRQ bit before sleep mode (SLPRQ = 1 and SLPAK = 1) is active.

After wake-up, the MSCAN waits for 11 consecutive recessive bits to synchronize to the CAN bus. As a consequence, if the MSCAN is woken-up by a CAN frame, this frame is not received.

The receive message buffers (RxFG and RxBG) contain messages if they were received before sleep mode was entered. All pending actions will be executed upon wake-up; copying of RxBG into RxFG, message aborts and message transmissions. If the MSCAN remains in bus-off state after sleep mode was exited, it continues counting the 128 occurrences of 11 consecutive recessive bits.

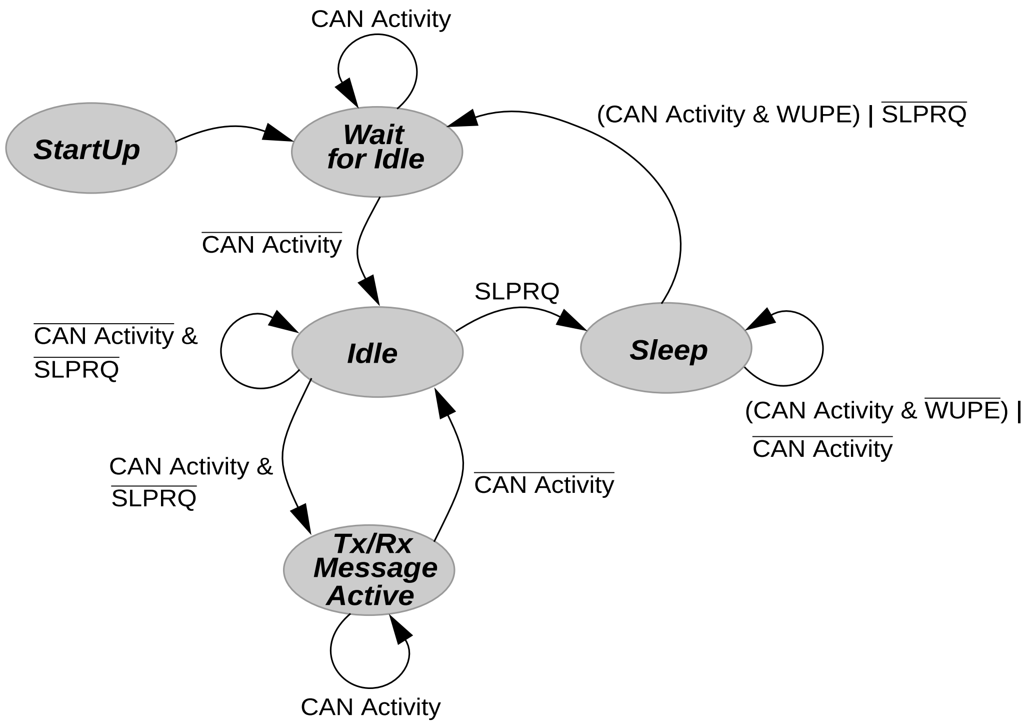


Figure 12-45. Simplified State Transitions for Entering/Leaving Sleep Mode

17.4.1.1 BDC Status and Control Register (BDCSCR)

This register can be read or written by serial BDC commands (READ_STATUS and WRITE_CONTROL) but is not accessible to user programs because it is not located in the normal memory map of the MCU.

	7	6	5	4	3	2	1	0
R	ENBDM	BDMACT	BKPTEN	FTS	CLKSW	WS	WSF	DVF
W		▨				▨	▨	▨
Normal Reset	0	0	0	0	0	0	0	0
Reset in Active BDM:	1	1	0	0	1	0	0	0

▨ = Unimplemented or Reserved

Figure 17-5. BDC Status and Control Register (BDCSCR)

Table 17-2. BDCSCR Register Field Descriptions

Field	Description
7 ENBDM	**Enable BDM (Permit Active Background Mode)** — Typically, this bit is written to 1 by the debug host shortly after the beginning of a debug session or whenever the debug host resets the target and remains 1 until a normal reset clears it. 0 BDM cannot be made active (non-intrusive commands still allowed) 1 BDM can be made active to allow active background mode commands
6 BDMACT	**Background Mode Active Status** — This is a read-only status bit. 0 BDM not active (user application program running) 1 BDM active and waiting for serial commands
5 BKPTEN	**BDC Breakpoint Enable** — If this bit is clear, the BDC breakpoint is disabled and the FTS (force tag select) control bit and BDCBKPT match register are ignored. 0 BDC breakpoint disabled 1 BDC breakpoint enabled
4 FTS	**Force/Tag Select** — When FTS = 1, a breakpoint is requested whenever the CPU address bus matches the BDCBKPT match register. When FTS = 0, a match between the CPU address bus and the BDCBKPT register causes the fetched opcode to be tagged. If this tagged opcode ever reaches the end of the instruction queue, the CPU enters active background mode rather than executing the tagged opcode. 0 Tag opcode at breakpoint address and enter active background mode if CPU attempts to execute that instruction 1 Breakpoint match forces active background mode at next instruction boundary (address need not be an opcode)
3 CLKSW	**Select Source for BDC Communications Clock** — CLKSW defaults to 0, which selects the alternate BDC clock source. 0 Alternate BDC clock source 1 MCU bus clock

Table 17-2. BDCSCR Register Field Descriptions (continued)

Field	Description
2 WS	**Wait or Stop Status** — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands. 0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active) 1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode
1 WSF	**Wait or Stop Failure Status** — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.) 0 Memory access did not conflict with a wait or stop instruction 1 Memory access command failed because the CPU entered wait or stop mode
0 DVF	**Data Valid Failure Status** — This status bit is not used in the MC9S08DV60 Series because it does not have any slow access memory. 0 Memory access did not conflict with a slow memory access 1 Memory access command failed because CPU was not finished with a slow memory access

17.4.1.2 BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ_BKPT and WRITE_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to Section 17.2.4, “BDC Hardware Breakpoint.”

17.4.2 System Background Debug Force Reset Register (SBDFR)

This register contains a single write-only control bit. A serial background mode command such as WRITE_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.

[3] Monotonicity and No-Missing-Codes guaranteed in 10 bit and 8 bit modes

[4] Based on input pad leakage current. Refer to pad electricals.

A.10 External Oscillator (XOSC) Characteristics

Table A-11. Oscillator Electrical Specifications (Temperature Range = –40 to 125°C Ambient)

Num	C	Rating	Symbol	Min	Typ[1]	Max	Unit
1	C	Oscillator crystal or resonator (EREFS = 1, ERCLKEN = 1					
		Low range (RANGE = 0)	f_{lo}	32	—	38.4	kHz
		High range (RANGE = 1) FEE or FBE mode [2]	$f_{hi\text{-}fll}$	1	—	5	MHz
		High range (RANGE = 1) PEE or PBE mode[3]	$f_{hi\text{-}pll}$	1	—	16	MHz
		High range (RANGE = 1, HGO = 1) BLPE mode	$f_{hi\text{-}hgo}$	1	—	16	MHz
		High range (RANGE = 1, HGO = 0) BLPE mode	$f_{hi\text{-}lp}$	1	—	8	MHz
2	—	Load capacitors	C_1 C_2	See crystal or resonator manufacturer’s recommendation.			
3	—	Feedback resistor					
		Low range (32 kHz to 100 kHz)	R_F	—	10	—	MΩ
		High range (1 MHz to 16 MHz)		—	1	—	MΩ
4	—	Series resistor					
		Low range, low gain (RANGE = 0, HGO = 0)	R_S	—	0	—	kΩ
		Low range, high gain (RANGE = 0, HGO = 1)		—	100	—	
		High range, low gain (RANGE = 1, HGO = 0)		—	0	—	
		High range, high gain (RANGE = 1, HGO = 1) ≥ 8 MHz		—	0	0	
		4 MHz		—	0	10	
		1 MHz		—	0	20	
5	T	Crystal start-up time [4]					
		Low range, low gain (RANGE = 0, HGO = 0)	$t_{CSTL\text{-}LP}$	—	200	—	ms
		Low range, high gain (RANGE = 0, HGO = 1)	$t_{CSTL\text{-}HGO}$	—	400	—	
		High range, low gain (RANGE = 1, HGO = 0)[5]	$t_{CSTH\text{-}LP}$	—	5	—	
		High range, high gain (RANGE = 1, HGO = 1)[4]	$t_{CSTH\text{-}HGO}$	—	15	—	
6	T	Square wave input clock frequency (EREFS = 0, ERCLKEN = 1)					
		FEE or FBE mode [2]	f_{extal}	0.03125	—	5	MHz
		PEE or PBE mode[3]		1	—	16	
		BLPE mode		0	—	40	

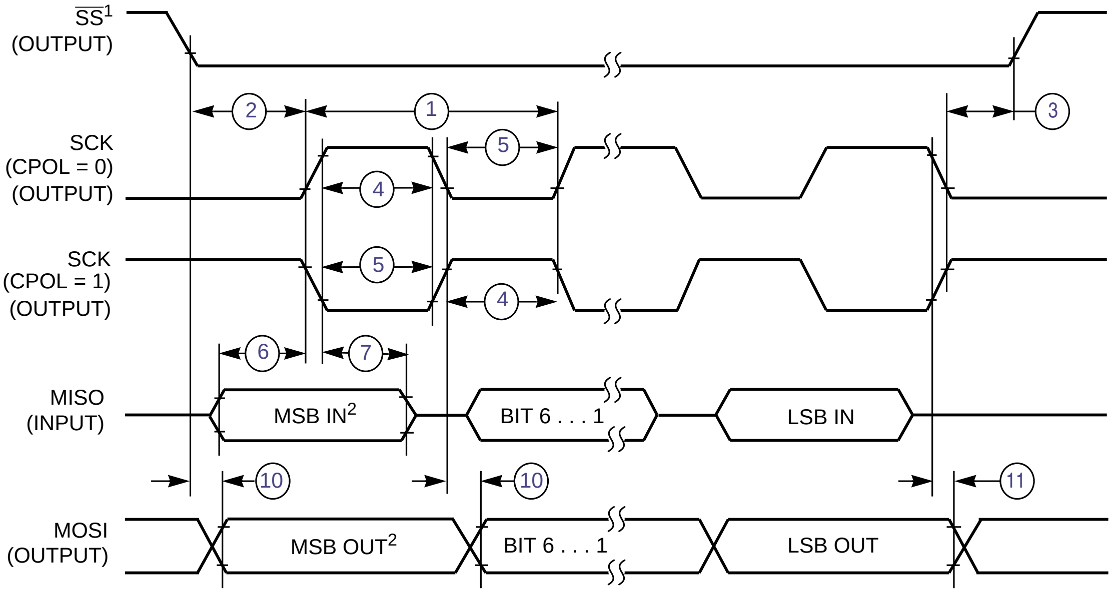
[1] Typical data was characterized at 3.0 V, 25°C or is recommended value.

[2] When MCG is configured for FEE or FBE mode, the input clock source must be divisible using RDIV to within the range of 31.25 kHz to 39.0625 kHz.

[3] When MCG is configured for PEE or PBE mode, input clock source must be divisible using RDIV to within the range of 1 MHz to 2 MHz.

[4] This parameter is characterized and not tested on each device. Proper PC board layout procedures must be followed to achieve specifications. This data will vary based upon the crystal manufacturer and board design. The crystal should be characterized by the crystal manufacturer.

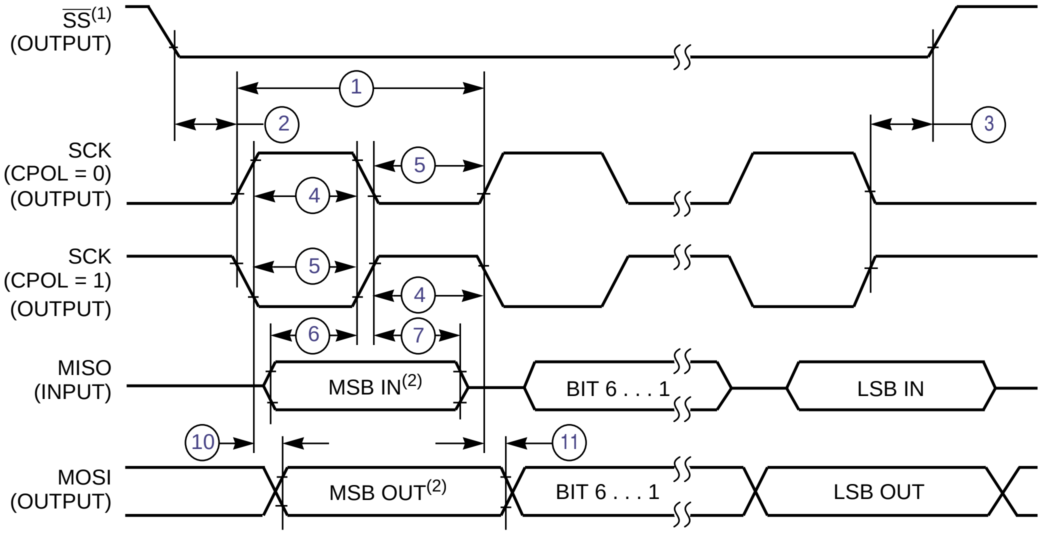
[5] 4 MHz crystal.



NOTES:

1. $\overline{\text{SS}}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-7. SPI Master Timing (CPHA = 0)



NOTES:

1. $\overline{\text{SS}}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-8. SPI Master Timing (CPHA = 1)

A.14.1 Radiated Emissions

Microcontroller radiated RF emissions are measured from 150 kHz to 1 GHz using the TEM/GTEM Cell method in accordance with the IEC 61967-2 and SAE J1752/3 standards. The measurement is performed with the microcontroller installed on a custom EMC evaluation board while running specialized EMC test software. The radiated emissions from the microcontroller are measured in a TEM cell in two package orientations (North and East). For more detailed information concerning the evaluation results, conditions and setup, please refer to the EMC Evaluation Report for this device.

The maximum radiated RF emissions of the tested configuration in all orientations are less than or equal to the reported emissions levels.

Table A-18. Radiated Emissions for 3M05C Mask Set

Parameter	Symbol	Conditions	Frequency	f_{osc}/f_{CPU}	Level[1] (Max)	Unit
Radiated emissions, electric field — Conditions -	V_{RE_TEM}	V_{DD} = 5 T_A = +25°C 64 LQFP	0.15 – 50 MHz	16 MHz Crystal 20 MHz Bus	18	dBμV
			50 – 150 MHz		18	
			150 – 500 MHz		13	
			500 – 1000 MHz		7	
			IEC Level		L	—
			SAE Level		2	—

[1] Data based on qualification test results.

Table C-2. Package Descriptions

Pin Count	Type	Abbreviation	Designator	Document No.
64	Low Quad Flat Package	LQFP	LH	98ASS23234W
48	Low Quad Flat Package	LQFP	LF	98ASH00962A
32	Low Quad Flat Package	LQFP	LC	98ASH70029A